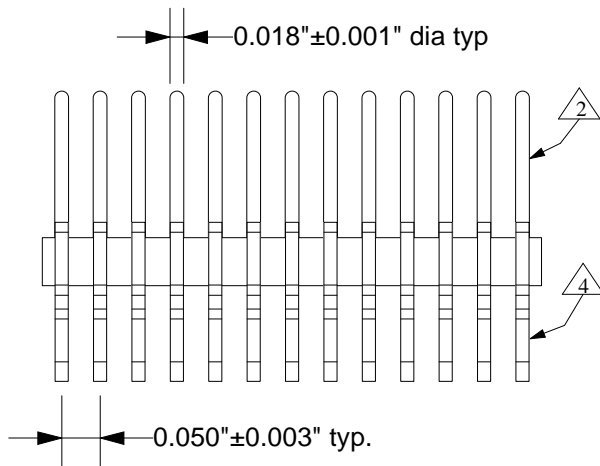
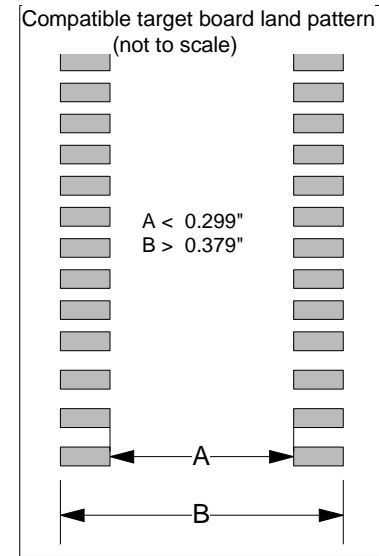
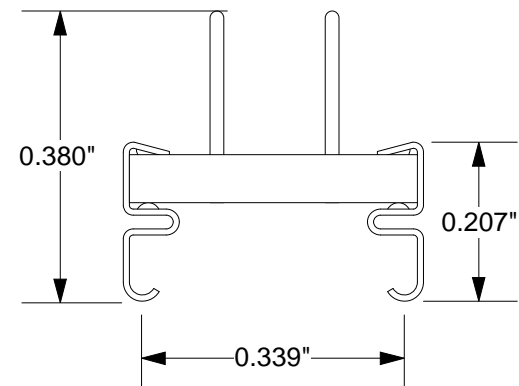


Top View




Side View



End View

- △1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- △2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- △4 Leads: material- BeCu Alloy 194; plating- 80/20 SnPb.

Description: SO surface mount emulator foot
 26 position (0.05" pitch) J-led surface mountable emulator foot, with Mini grid array (MGA) pin interface.

SF-SO26D-J-01 Drawing		Status: released	Scale: 4:1	Rev: A
 © 1998 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100	Drawing: P. LeBeau		Date: 3/3/98	
	File: SF-SO26D-J-01 Dwg			Modified:

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.